CALIFORNIA INSTITUTE OF TECHNOLOGY VLBA Correlator Memorandum

To:VLBA Correlator GroupFrom:Steve Kator, Dave Fort, Martin EwingDate: 29 July 1985Subject:Subsystem Estimates

This memo provides further descriptions of major portions of the VLBA correlator architecture of Memo VCO41 and some more recent design information. These include estimates of chips, materials costs, and power dissipation. NOTE: Estimates do not include design costs or other labor costs.

STATION ELECTRONICS. Table I shows the Station Electronics breakdown which is meant to be closely similar to the design presented in VCO41. The cost estimates supplied as a deliverable under Phase A1 of the Caltech contract from NRAO are based on this table. The item labelled "Criss-cross crates" did not appear in the Memo; it is a passive subsystem that simply reorganizes input cables, arranged, for example, by DPS number to outputs arranged by channels, etc.

Table II reflects a design approach investigated after VC041 was published. In this system, the large crossbar and criss-cross assemblies are eliminated in favor of carrying delay- and phase-corrected signals for all 24 possible DPS units to the correlator electronics. Interconnections are substantially simplified compared with the Table I design, and costs are somewhat reduced even though more delay and phase boards are required.

Table III is our latest design, reflecting the interconnection scheme of Table II with the addition of a gate array implementation of the delay and phase circuits. System size is reduced from 2 racks to 1, and all major functions are accommodated on one type of board. This design appears to offer considerable system simplification and cost savings compared with the "Table II" or "Table I" designs.

CORRELATOR ELECTRONICS. Table IV is our current breakdown of the Correlator Electronics subsystem. It is somewhat more detailed than the description in VCO41, but it retains essentially the same design features. A "Data Concentrator" has been added to interface between the DR11-W TOP Input interface and the COP processors in the ECAs. This is a small 68000 system that buffers and switches incoming data. Refer to memo VCO51.

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| VLBA STATION ELECTRONICS I (Architecture Repor SUBSYSTEM ESTIMATE | <u>t Yersion)</u> 7/29/85 |
| I/O BOARD Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 53 \$462 19. W |
| DELAY/PHASE BOARD Number of switch VLSI chips: Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 3 335 \$1,340 68. W |
| PHASE CAL BOARD Number of switch VLSI chips: Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 3 215 \$845 44. W |
| CONTROLLER BOARD Estimated cost: Estimated power dissipation: | \$2,000 20. W |
| DELAY/PHASE CRATE Number of I/O boards: Number of Delay/phase boards: Number of Phase Cal boards: Number of Controllers: Estimated materials cost (inc. backplane hdwe.): Estimated power dissipation: | 2 10 2 1 \$19,364 826. W |
| DELAY/PHASE RACK Number of Delay/phase crates: Estimated materials cost (inc. rack and pwr. sup.): Estimated power dissipation: | 4 \$84,950 3,650.W |
| CHANNEL CROSSBAR BOARD Number of switch VLSI chips: Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 16 63 \$804 24. W |
| CHANNEL CROSSBAR CRATE Number of Channel Crossbar boards: Number of Controller boards: Estimated materials cost (inc. backplane hdwe.): Estimated power dissipation: | 10 1 \$11,040 260. W |

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| CRISS-CROSS CRATES (estimated materials costs) Criss-cross 1 (24x3x16 pair in, 16x3x24 pair out): Criss-cross 2 (16x4x20 pair in, 20x4x16 pair out): Criss-cross 3 (40x4x16 pair in, 32x4x20 pair out; 2 c Subtotal estimated materials cost (inc. packaging hd | \$696 \$928 rates): \$1,856 we.): \$4,400 |
| CHANNEL CROSSBAR RACK Number of Channel Crossbar crates: Number of Criss-cross crates: Estimated materials cost (inc. rack and pwr. sup.): Estimated power dissipation: | 2 4 \$28,000 575. W |
| CABLING (estimated materials costs) Stations to Criss-cross 1 (24x3x16 pair, 15 m): Criss-cross 1 to Delay/phase rack (16x3x24 pair, 10 Delay/phase rack to Criss-cross 2 (16x4x20 pair, 10 Criss-cross 2 to Channel Crossbar (20x4x16 pair, 2 r Channel Crossbar to Criss-cross 3 (40x4x16 pair, 2 r Criss-cross 3 to Correlator Electronics (32x4x20 pai Subtotal estimated materials cost (inc. connectors): | \$4,223 m): \$2,808 m): \$3,744 m): \$1,042 m): \$2,083 ir,10 m):\$7,488 \$21,400 |
| COMPLETE SUBSYSTEM Number of Delay/phase racks: Number of Channel Crossbar racks: Estimated cost of test bed and prototyping materials: Total estimated materials cost: Total estimated power dissipation: | 2 1 \$9,500 \$228,800 7875. W |
| YLBA STATION ELECTRONICS II SUBSYSTEM ESTIMATE | 7/29/85 |
| I/O BOARD Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 43 \$422 19. W |
| DELAY/PHASE BOARD Number of switch VLSI chips: Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 3 335 \$1,340 68.₩ |
| PHASE CAL BOARD Number of switch VLSI chips: Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 3 175 \$765 36. W |

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| CONTROLLER BOARD Estimated cost: Estimated power dissipation: | | \$2,000 20.W |
| DELAY/PHASE CRATE Number of I/O boards: Number of Delay/phase boards: Number of Phase Cal boards: Number of Controllers: Estimated materials cost (inc. backplane hdwe.): Estimated power dissipation: | | 3 12 3 1 \$23,000 989. W |
| DELAY/PHASE RACK Number of Delay/phase crates: Estimated materials cost (inc. rack and pwr. sup.): Estimated power dissipation: | | 4 \$100,750 4,350. W |
| CABLING (estimated materials costs) Stations to Delay/phase rack (24x3x16 pair, 15 m): Delay/phase rack to Corr. Elec. (24x16x8 pair, 10 m Subtotal estimated materials cost (inc. connectors): |): ; | \$4,200 7,500 \$11,700 |
| COMPLETE SUBSYSTEM Number of Delay/phase racks: Estimated cost of test bed and prototyping materials: Total estimated materials cost: Total estimated power dissipation: | | 2 \$8,800 \$222,000 8,700. W |
| YLBA STATION ELECTRONICS III (Correlator Memo SUBSYSTEM ESTIMATE | YC04 | <mark>9 Yersion)</mark> 7/29/85 |
| DELAY/PHASE/PCAL BOARD Number of switch VLSI chips: (Production cost per switch VLSI chip: Number of delay/phase/pcal VLSI chips: (Production cost per delay/phase/pcal VLSI chip: Number of standard LSI chips: Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | | 11 \$12.) 8 \$35.) 80 37 \$1,215 32. W |
| CONTROLLER BOARD | | A |

| Estimated cost: | \$2,000 |
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| Estimated power dissipation: | 20. W |

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| DELAY/PHASE/PCAL CRATE Number of Delay/phase/pcal boards: Number of Controllers: Estimated materials cost (inc. backplane hdwe.): Estimated power dissipation: | 1 \$22,40 53 | 6 1 0 2. W |
| DELAY/PHASE/PCAL RACK Number of Delay/phase/pcal crates: Estimated materials cost (inc. rack and pwr. sup.): Estimated power dissipation: | \$70,40 1,75 | 3 0 0. W |
| CABLING (estimated materials costs) Stations to Delay/phase/pcal rack (24x2x24 pair, 15 r Delay/phase/pcal rack to Corr. Elec. (16x6x32 pair, Subtotal estimated materials cost (inc. connectors): | m): \$4,10 10 m): 6,10 : \$10,20 | 0 0 0 |
| COMPLETE SUBSYSTEM Number of Delay/phase/pcal racks: Estimated cost of test bed and prototyping materials: Total estimated materials cost: Total estimated power dissipation: | \$6,40 \$87,00 1,75 | 1 0 0 0.₩ |
| YLBA CORRELATOR ELECTRONICS SUBSYSTEM ESTIMATE | 7/17/8 | 5 |
| INPUT BOARD Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 6 \$47 1 | 2 5 0. W |
| CORRELATOR BOARD Number of correlator VLSI chips: (Production cost per correlator VLSI chip: Number of switch VLSI chips: (Production cost per switch VLSI chip: Number of standard LSI chips: Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 3 \$7 \$1 \$3,16 2 | 2 0.) 8 2.) 4 7 5. W |
| DSP BOARD Number of standard LSI chips: Number of standard MSI chips: Estimated materials cost: Estimated power dissipation: | 3 4 \$80 2 | 8 8 7 5. W |

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| COP BOARD Estimated cost: Estimated power dissipation: | | \$2,000 15. W |
| PARALLEL OUTPUT BOARD Estimated cost: Estimated power dissipation: | | \$1,500 10. W |
| ELEMENTARY CORRELATOR ARRAY CRATE Number of Input boards: Number of Correlator boards: Number of DSP boards: Number of COP boards: Number of Parallel Output boards: Estimated materials cost (inc. backplane hdwe.): Estimated power dissipation: | | 1 13 4 1 \$50,300 460. W |
| C.E. QUADRANT RACK Number of Elementary Correlator Array crates: Estimated materials cost (inc. rack & power sup.): Estimated power dissipation: | | 4 \$207,500 2,000. W |
| PARALLEL INPUT BOARD Estimated cost: Estimated power dissipation: | | \$1,000 10. W |
| DATA CONCENTRATOR CONTROLLER BOARD Estimated cost: Estimated power dissipation: | | \$2,000 15. W |
| DR11-W INTERFACE BOARD Estimated cost: Estimated power dissipation: | | \$1,500 18.W |
| DATA CONCENTRATOR CRATE AND RACK Number of Parallel Input Boards: Number of Data Concentrator Controller Boards: Number of DR11-W Boards: Estimated cost (w/backplanes, cables, p.s. & 0.25 r Estimated power dissipation: | ack): | 16 1 \$23,200. 200. W |
| COMPLETE SUBSYSTEM Number of C.E. Quadrant racks: Number of Data Concentrator racks per quadrant*: Estimated cost of test bed and prototype mat'ls: Total estimated materials cost: Total estimated power dissipation: | | 4 1/4 \$18,000 \$871,200 8,200. W |

* There is just one Data Concentrator for the entire correlator.